## **PATENT**

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Valeriy Sukharev et al.	)
Filed: July 8, 2003	) Certificate of Mailing by "Express Mail"
For: COPPER-LOW-K DUAL DAMASCENE INTERCONNECT WITH IMPROVED RELIABILITY	Mailing Label Number: EV335604370US  Date of Deposit: July 8, 2003  I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office Box Addressee" service under 35 CFR 1.10 on the date indicated above and is addressed to the Commissioner for Palents, P.O. Box 1450, Alexandrica 14722313-1450.  James R. 6-ofty, Reg. No. 39,979
Art Unit: Not yet assigned	
Atty Docket No.: 03-0509	ý

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In accordance with Applicant's duty of candor under 37 CFR §1.56 and in compliance with 37 CFR §1.97 and §1.98, Applicant is not aware of any material prior art but, in an abundance of caution and candor, Applicant submits the present Information Disclosure Statement including the attached Form PTO-1449. Copies of the listed references are included herewith. This Information Disclosure Statement and the enclosures constitute a bona fide attempt to comply with 37 CFR §1.97 and §1.98.

This Information Disclosure Statement is being filed along with the patent application and constitutes a bona fide attempt to comply with 37 CFR §1.97 and §1.98

Respectfully submitted,

Date: <u>July 8, 2003</u>

James R. Foley, Reg. No. 39,97

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